

### ***Amendments to the Claims***

The listing of claims below will replace all prior versions and listings of claims in the application.

1. (Canceled)

2. (Currently Amended) A method ~~to produce~~ for producing an electronic components component with closely adjacent electrodes on a ~~substrate such that the structuring of the~~ electrodes is achieved using the following steps: substrate, comprising:

a) depositing a first metal layer onto the substrate;

b) structuring a first photo lacquer on a surface of the first metal layer; layer except a portion of the surface of the first metal layer;

c) etching the portion of the surface of the first metal layer;

e) d) undercut etching the first metal layer such so that overhangs are an overhang is formed in by the first photo lacquer by means of controlled undercutting of the metal; lacquer;

d) e) exposing a surface of the first photo lacquer and the portion of the surface thus produced of the first metal layer to a first metal vapor; vapor so that a second metal layer is formed on the surface of the first photo lacquer and the portion of the surface of the first metal layer except in a space between the overhang and the substrate; and

e) f) removing the first photo lacquer with its and the second metal layer. layer formed on the surface of the first photo lacquer.

3. (Currently Amended) The method of claim 2 2, further comprising:

a) g) depositing ~~a transparent~~ an organic semi-conductor on the first metal layer, the second metal layer, and the substrate;

h) ~~and a transparent~~ depositing an insulator on the ~~surface thus produced;~~ organic semi-conductor;

~~b) i)~~ depositing a second photo lacquer ~~is deposited on an upper side, and performing photo lithography on an underside;~~ the insulator;

j) removing a first portion of the second photo lacquer that is opposite other than the first metal layer and the second metal layer;

~~e) k)~~ depositing a second metal vapor ~~onto the~~ so that a third metal layer is formed on a surface thus produced; of the second photo lacquer and a surface of the insulator; and

~~d) l)~~ removing the ~~remaining~~ second photo lacquer ~~with its~~ and the third metal layer, layer formed on the surface of the second photo lacquer.

~~e)~~ etching at least one contact until it is exposed.

4. (Currently Amended) The method of claim 2 2, further comprising:

a) g) ~~etching holes or grooves~~ a hole into the substrate at ~~those positions without metal,~~ a position other than a position of the first metal layer and the second metal layer;

b) h) depositing a ~~second thin~~ third metal layer, layer onto the substrate, the first metal layer, and the second metal layer;

~~e) i)~~ applying an insulator, insulator onto the third metal layer;

d) j) etching a portion of the insulator on an upper side of the substrate; at the position of the first metal layer and the second metal layer;

e) k) applying an organic semi-conductor ~~and sealing the surface;~~ onto the third metal layer and the insulator;

l) applying a sealing layer onto the organic semi-conductor; and

f) m) exposing ~~at least one gate~~ the third metal gate at a position of the hole using a photolithographic process.

5. (New) The method of claim 2, wherein the substrate is made of at least one of a polymer film and a glass.

6. (New) The method of claim 2, wherein the first metal layer is made of at least one of chromium and gold.

7. (New) The method of claim 2, wherein the second metal layer is made of gold.

8. (New) The method of claim 2, further comprising:

g) depositing an organic semi-conductor on the first metal layer, the second metal layer, and the substrate;

h) depositing an insulator on the organic semi-conductor;

i) depositing a second metal vapor so that a third metal layer is formed on a surface of the insulator;

j) structuring a first portion of a second photo lacquer on a first portion of a surface of the third metal layer that is opposite other than the first metal layer and the second metal layer;

k) removing a portion of the third metal layer opposite the first metal layer and the second metal layer; and

l) removing the second photo lacquer.

9. (New) The method of claim 8, further comprising, before the removing the portion of the third metal layer:

m) structuring a second portion of the second photo lacquer on a second portion of the surface of the third metal layer that is opposite at least one of a portion of the first metal layer and a portion of the second metal layer.

10. (New) The method of claim 3, wherein the third metal layer is made of gold.

11. (New) The method of claim 3, wherein the substrate is transparent, the organic semi-conductor is transparent, and the insulator is transparent, and wherein the first portion of the second photo lacquer is identified by a photolithographic process in which a light impinges the substrate on a surface opposite a surface adjacent to the first metal layer, the second metal layer, and the organic semi-conductor.

12. (New) The method of claim 3, further comprising, before the depositing the second metal vapor:

m) removing a second portion of the second photo lacquer that is opposite at least one of a portion of the first metal layer and a portion of the second metal layer.

13. (New) The method of claim 4, wherein the third metal layer is made of gold.

14. (New) An electronic component with closely adjacent electrodes, comprising:

a substrate;

a first electrode formed on the substrate;

a second electrode formed on the substrate in which a separation between the first electrode and the second electrode is between ten nanometers and two thousand nanometers;

an organic semi-conductor formed on the substrate, the first electrode, and the second electrode;

an insulator formed on the organic semi-conductor; and

a third electrode formed on the insulator opposite the separation between the first electrode and the second electrode;

wherein the separation between the first electrode and the second electrode is formed by forming a photo lacquer layer on a portion of a first metal layer formed on the substrate, etching a portion of the first metal layer, undercut etching the first metal layer to produce an overhang of the photo lacquer layer, depositing a second metal layer on the substrate at a position of the portion of the first metal layer, and removing the photo lacquer layer.

15. (New) The electronic component of claim 14, wherein the third electrode formed on the insulator opposite the separation between the first electrode and the second electrode is also opposite a portion of the first electrode and opposite a portion of the second electrode.

16. (New) The electronic component of claim 14, wherein the substrate is made of at least one of a polymer film and a glass.

17. (New) The electronic component of claim 14, wherein the first electrode is made of at least one of chromium and gold.

18. (New) The electronic component of claim 14, wherein the third electrode is made of gold.

19. (New) An electronic component with closely adjacent electrodes, comprising:

a substrate;

a first electrode formed on the substrate;

a second electrode formed on the substrate in which a separation between the first electrode and the second electrode is between ten nanometers and two thousand nanometers;

a third electrode formed in a hole in the substrate in the separation between the first electrode and the second electrode;

an insulator formed on the third electrode;

an organic semi-conductor formed on the first electrode, the second electrode, and the insulator; and

a sealing layer formed on the organic semi-conductor;

wherein the separation between the first electrode and the second electrode is formed by forming a photo lacquer layer on a portion of a first metal layer formed on the substrate, etching a portion of the first metal layer, undercut etching the first metal layer to produce an overhang of the photo lacquer layer, depositing a second metal layer on the substrate at a position of the portion of the first metal layer, and removing the photo lacquer layer.

20. (New) The electronic component of claim 19, wherein the substrate is made of at least one of a polymer film and a glass.

21. (New) The electronic component of claim 19, wherein the first electrode is made of at least one of chromium and gold.

22. (New) The electronic component of claim 19, wherein the third electrode is made of gold.